MACHINED BOARD STACKING STRIPS

Mates with:
SS, SD, HSS, SL, SDL, ESS, ESD

Features:
- Low profile design achieves (3.89 mm) .153" board spacings when mated with SL Series.
- Approach the reliability of a permanent connection with the flexibility of a separable connection.

Specifications:

Insulator Material:
Black Glass Filled Polyester (BBS, BBD, BBL)
Black High Temp Nylon (BDL)
Black Liquid Crystal Polymer (BHS)

Temperature Range:
-55°C to +125°C

Terminal Material:
Phosphor Bronze or Brass

Plating:
Au or Sn over 50µ" (1.27 µm) Ni
RoHS Compliant:
Yes

Lead-Free Solderable:
Wave only (BBS, BBD, BBL, BDL)
Wave, or reflow with all Au (BHS)

Recognitions:
For complete scope of recognitions see www.samtec.com/quality

Note: Some lengths, styles and options are non-standard, non-returnable.

<table>
<thead>
<tr>
<th>TYPE STRIP</th>
<th>NO. PINS PER ROW</th>
<th>PLATING OPTION</th>
<th>LEAD STYLE</th>
</tr>
</thead>
<tbody>
<tr>
<td>BBS</td>
<td>1 (2.54) .100 x No. of Positions</td>
<td>–G =20 µ&quot; (0.51 µm) Gold</td>
<td>–A Z = (5.33 mm) .210&quot;</td>
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<tr>
<td>BBL</td>
<td>1 (2.54) .100 x No. of Positions</td>
<td>–T =Tin</td>
<td>–B Z = (8.51 mm) .335&quot;</td>
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<tr>
<td>BHS</td>
<td>1 (2.54) .100 x No. of Positions</td>
<td>–G =20 µ&quot; (0.51 µm) Gold</td>
<td>–C Z = (14.86 mm) .585&quot;</td>
</tr>
<tr>
<td>BBD</td>
<td>1 (2.54) .100 x No. of Positions</td>
<td>–G =20 µ&quot; (0.51 µm) Gold</td>
<td>–E Z = (1.78 mm) .070&quot;</td>
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<tr>
<td>BDL</td>
<td>1 (2.54) .100 x No. of Positions</td>
<td>–G =20 µ&quot; (0.51 µm) Gold</td>
<td>–F Z = (2.16 mm) .085&quot;</td>
</tr>
</tbody>
</table>

Due to technical progress, all designs, specifications and components are subject to change without notice.